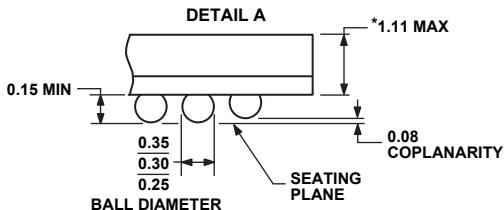
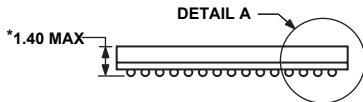
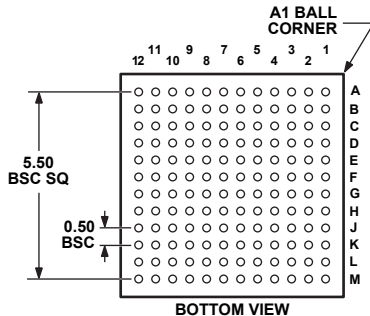
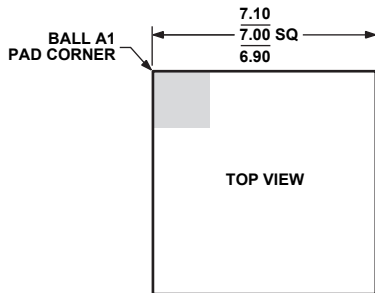


144-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-144-4)

Dimensions shown in millimeters

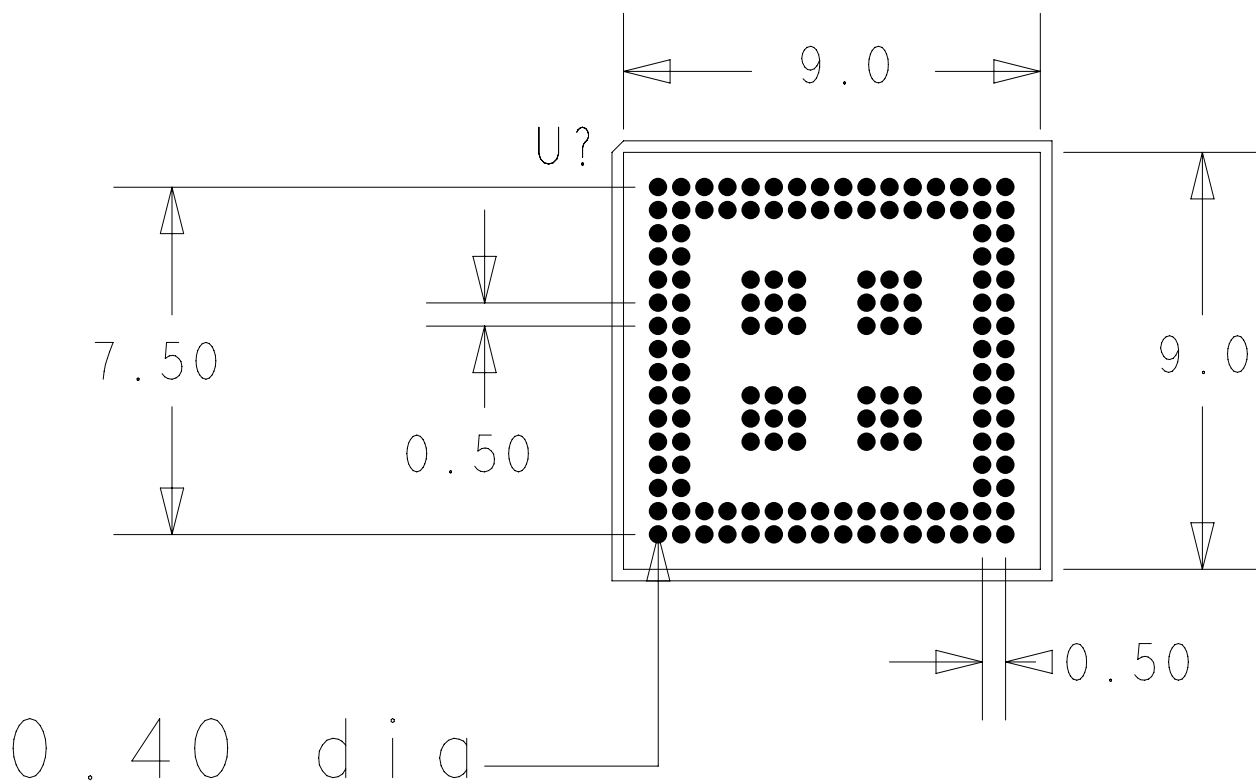


*COMPLIANT WITH JEDEC STANDARDS MO-195-BD WITH
EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.

Analog Devices

BC - 148

REV A



(Dim. are in MM)

LAST MODIFIED 09/04/07